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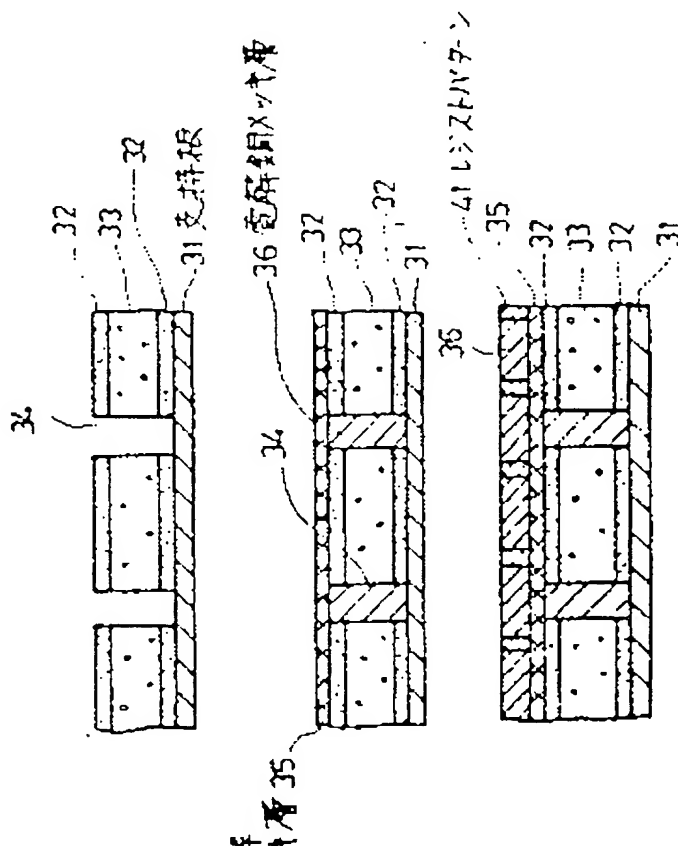
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### (54) MULTILAYER PRINTED BOARD

(57) Abstract:

**PURPOSE:** To transmit a signal at high speed by a low dielectric constant, and to use a base substrate consisting of an organic material such as a glass epoxy resin by composing an insulating layer of an adhesive layer made up of a sheet-shaped foamed fluoroplastic resin layer coated or impregnated with a thermosetting resin.

**CONSTITUTION:** An adhesive layer (a prepreg layer) in which a through-hole 34 is bored and worked to a material, in which foamed fluoro-plastics 33 are coated or impregnated with a thermosetting resin 32 under the state of a stage B, by using punching working is pressed and laminated. Pressure bonding is conducted by curing under pressure at the curing temperature (170-200°C) of a conventional thermosetting resin by the pressure laminating of the adhesive layer. Consequently, a substrate



consisting of an organic material such as a glass epoxy resin can be employed besides a ceramic substrate as a substrate material, and the degree of freedom of the selection of the substrate is improved. Since the foamed fluoroplastics are used, the bubbles of air are contained in the foamed fluoroplastics, and the dielectric constant of the foamed fluoroplastics displays a value between the value of 2.1 of fluoroplastics and the value of 1 of the dielectric constant of air, and a signal can be transmitted at high speed.

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